

EAST - [resistor wsp. 1]

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- ④ Drafts
- ④ Pending
- ④ Active
 - ④ L1: (1) ("6685080").PN.
 - ④ L2: (7893) solder\$1.clm. a
 - ④ L3: (167) 2 and (replac\$3
 - ④ L4: (10) 3 and tube\$1
 - ④ L5: (183) 2 and ((replac\$1
 - ④ L7: (3) 6 and tube\$1
 - ④ L8: (69) 8 and ball\$1.cla

Failed

• Saved

2 (0) ("(thin adj film)nearresistor").PN
3 (0) ("(thin adj film)nearresistor").PN
2 (150130) thin adj film
2 (14857) (thin adj film) and resistor
2 (2054) ((thin adj film) and resistor
2 (1735) (((thin adj film) and resista
2 (801) (((thin adj film) and resista
2 (499) (((((thin adj film) and resist
2 (124) ((((((thin adj film) and resist
2 (34) ((((((thin adj film) and resist

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U	P	T	P	Document ID	Issue Date	Pages	Title	Current CR	Current XN	Retrieval	Inventor	S	C	R	G	B
1	P	F	F	US 20040180559	20040916	14	Hinge connector, and circuit board connected	439/17			Haragawa, Masaaki	F	F	F	F	F
2	P	F	C	US 20040169275	20040902		Area-array device assembly with pre-applied	257/737			Danvir, Janice et al.	C	F	F	F	F
3	P	F	F	US 20040124004	20040701		Decoupled signal-power substrate architecture	174/255	174/258, 257/691		Nair, Rajendran et al.	F	F	F	F	F
4	P	F	F	US 20040056078	20040325	15	Individual selective rework of defective BGA	228/245	228/105, 228/41		Kee, Kwan Yew et al.	F	F	F	F	F
5	P	F	F	US 20040007384	20040115		Electronic device	174/260			Soga, Tasao et al.	F	F	F	F	F
6	P	F	C	US 20030224197	20031204		Solder	428/570	428/652, 428/672		Soga, Tasao et al.	F	F	F	F	F
7	P	F	F	US 20030178716	20030925		Light thin stacked package semiconductor	257/686	257/E23.12		Maeda, Takehiko et al.	F	F	F	F	F
8	P	F	C	US 20030141593	20030731		Flip-chip without bumps and polymer for board a	257/750	257/781, 257/786		Zuniga-Ortiz, Edgar R. et al.	C	F	F	F	F
9	P	F	F	US 20030127729	20030710		Stacked semiconductor device structure	257/723	257/686, 257/738		Fukumoto, Takakazu et al.	F	F	F	F	F
10	P	F	C	US 20030080392	20030501		Bumpless wafer scale device and board assemb	257/503	257/690, 257/E23.02		Zuniga-Ortiz, Edgar R. et al.	F	F	F	F	F
11	P	F	F	US 20030027415	20030206		Ball grid assembly with solder columns	438/613	257/E21.50		Heinen, Katherine G.	F	F	F	F	F
12	P	F	F	US 20030116			Method and apparatus	438/106	257/E21.50		Hotchkiss, Gregory	F	F	F	F	F